

AMENDMENTS TO THE CLAIMS

The following is a complete listing of the claims, which replaces all previous versions of the claims.

1. (previously presented). A remote server management controller disposed in a managed server, the remote server management controller comprising:
 - an IOP;
 - an embedded JTAG master that is controllable by the IOP, the embedded JTAG master having a JTAG interface; and
 - at least one integrated circuit disposed in the managed server and connected for operative communication to the JTAG interface, andwherein the JTAG master is configured to be accessed remotely through the remote server management controller to provide communication between a remote computer and the at least one integrated circuit via the JTAG interface.
2. (previously presented). The remote server management controller of claim 1 wherein the JTAG interface comprises an ITP interface that uses an ITP testing methodology.
3. (previously presented). The remote server management controller of claim 1 wherein the JTAG interface comprises an ICE interface that uses an ICE testing methodology.
4. (original). The remote server management controller of claim 1 wherein the at least one integrated circuit comprises a microprocessor.

5. (original). The remote server management controller of claim 1 wherein the at least one integrated circuit comprises a component of a chipset.
6. (previously presented). The remote server management controller of claim 1 wherein the JTAG master is configured to program the at least one integrated circuit.
7. (previously presented). The remote server management controller of claim 1 wherein the IOP is configured to be programmed to control the JTAG master to perform an initial test of the at least one integrated circuit when the managed server is initially powered up.
8. (original). The remote server management controller of claim 1 wherein the IOP is programmed with descriptive data about the at least one integrated circuit.
9. (previously presented). A managed server, comprising:
 - a motherboard having at least one integrated circuit disposed thereon;
 - a remote server management controller in operable communication with the managed server, the remote server management controller comprising:
 - an IOP; and
 - an embedded JTAG master that is controllable by the IOP, the embedded JTAG master having a JTAG interface, the at least one integrated circuit connected for operative communication to the JTAG interface,

wherein the JTAG master is configured to be accessed remotely through the remote server management controller to provide communication between a remote computer and the at least one integrated circuit via the JTAG interface.

10. (previously presented). The managed server of claim 9 wherein the JTAG interface comprises an ITP interface that uses an ITP testing methodology.

11. (original). The managed server of claim 9 wherein the at least one integrated circuit comprises a microprocessor.

12. (previously presented). The managed server of claim 9 wherein the JTAG master is configured to program the at least one integrated circuit.

13. (original). The managed server of claim 9 wherein the at least one integrated circuit comprises a component of a chipset.

14. (previously presented). The managed server of claim 9 wherein the IOP is configured to be programmed to control the JTAG master to perform an initial test of the at least one integrated circuit when the managed server is initially powered up.

15. (original). The managed server of claim 9 wherein the IOP is programmed with descriptive data about the at least one integrated circuit.

16. (previously presented). A method of communicating with an integrated circuit in a managed server, the managed server having a remote server management controller in operative communication therewith, the remote server management controller having an IOP and a JTAG master disposed thereon for operative communication with each other, the JTAG master having a JTAG interface connected for operative communication to the integrated circuit, the method comprising the acts of:

receiving data at the IOP of the remote server management controller;
transmitting the data from the IOP to the JTAG master; and
transmitting the data from the JTAG master to the integrated circuit via the
JTAG interface.

17. (previously presented). The method of claim 16, further comprising the act of programming the IOP to control the JTAG master to perform a boundary scan of the integrated circuit when the managed server is turned on.

18. (original). The method of claim 16 further comprising the act of programming the IOP with descriptive data about the integrated circuit.

19. (original). The method of claim 16 further comprising the act of programming the integrated circuit.

20. (previously presented). The method of claim 16 wherein the recited acts are performed preformed in the recited order.
21. (previously presented). A method of using a computer comprising:
connecting a computer to a remote server management controller disposed in a
managed server; and
communicating with an integrated circuit disposed in the managed server via a JTAG
interface associated with the remote server management controller.
22. (previously presented). The method, as set forth in claim 21, wherein communicating with the integrated circuit is controlled by an IOP.
23. (previously presented). The method, as set forth in claim 21, wherein the integrated circuit comprises a microprocessor.
24. (previously presented) A method of manufacturing a computer comprising:
disposing a remote server management controller in a server, the remote server
management controller comprising:
an IOP;
an embedded JTAG master that is controllable by the IOP, the embedded
JTAG master having a JTAG interface; and
an integrated circuit disposed in the managed server and connected for
operative communication to the JTAG interface, and

wherein the JTAG master is configured to be accessed remotely through the remote server management controller to provide communication between a client computer and the integrated circuit via the JTAG interface.

25. (previously presented). The method, as set forth in claim 24, wherein the integrated circuit is located on a motherboard.